

## PATENT APPLICATION

Attorney Docket: 54364

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Gupta, et al.

Serial No.: 09/847,667

Filed: 5/1/2001

For: Method for Bonding Wafers to  
Produce Stacked Integrated  
Circuits

Group Art Unit: 2827

Examiner: James Mitchell

**RESPONSE TO OFFICE ACTION**Hon. Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Sir:

In reply to the Office Action dated 1/17/03, in the above-identified patent application, Applicant submits the following Remarks. The period for response to this office action having been extended by three months by the accompanying petition for extension of time. Applicant respectfully requests that the Examiner reconsider the grounds for rejection stated in the Office Action.